



MICROCHIP

QUALIFICATION PLAN SUMMARY

PCN #: MFOL-19OLWR204

**Date:
March 12, 2026**

Qualification of UAT as an additional bumping site and UNIS as an additional Backend Process (BE2) for PAC1931T-I/J6CX, PAC1934T-I/J6CX, PAC1933T-I/J6CX, PAC1932T-I/J6CX, PAC1941T-1E/J6CX, PAC1941T-2E/J6CX, PAC1942T-1E/J6CX, PAC1942T-2E/J6CX, PAC1943T-E/J6CX, PAC1944T-E/J6CX, PAC1951T-1E/J6CX, PAC1951T-2E/J6CX, PAC1952T-1E/J6CX, PAC1952T-2E/J6CX, PAC1953T-E/J6CX, PAC1954T-E/J6CX catalog part numbers (CPN) available in 16L WLCSP (2.215x2.16x0.7mm) package.



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Package Qualification Plan

Purpose: Qualification of UAT as an additional bumping site and UNIS as an additional Backend Process (BE2) for PAC1931T-I/J6CX, PAC1934T-I/J6CX, PAC1933T-I/J6CX, PAC1932T-I/J6CX, PAC1941T-1E/J6CX, PAC1941T-2E/J6CX, PAC1942T-1E/J6CX, PAC1942T-2E/J6CX, PAC1943T-E/J6CX, PAC1944T-E/J6CX, PAC1951T-1E/J6CX, PAC1951T-2E/J6CX, PAC1952T-1E/J6CX, PAC1952T-2E/J6CX, PAC1953T-E/J6CX, PAC1954T-E/J6CX catalog part numbers (CPN) available in 16L WLCSP (2.215x2.16x0.7mm) package.

CCB No.: 8147

<u>Mics.</u>	Assembly site	Bump: UAT Back End Process (BE2): UNISEM
	MP Code (MPC)	VA7A1T6CXA00
	Part Number (CPN)	PAC1934T-I/J6CX
	MSL information	MSL-1
	Assembly Shipping Media (T/R, Tube/Tray)	T/R
	Base Quantity Multiple (BQM)	5000
<u>PKG</u>	Package Type	WLCSP
	Pin/Ball Count	16
	PKG width/size	2.215x2.16
	Solder Ball Material	SAC405
	Solder Ball Pitch/Size	500/300
	Polymer Material	PI
	Polymer Thickness	7.5
	UBM Deposition Method	sputter/plated
	UBM Thickness	Ti(0.12)/Cu(0.2) + plated Cu(8.6)
	UBM Opening Diameter	300um
	RDL Deposition method	sputter/plated
RDL Thickness	Ti(0.12)/Cu(0.2) + plated Cu(6)	

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	# of CSP lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instruction
Moisture Sensitivity	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. Perform optical analysis using 45 samples per lot. (MSL-1, 60C)	77 dice	5	3	82	0	15	Spares should be properly identified.
HAST, Unbiased	"JESD22-A118. +130°C/85% RH for 96 hours. Electrical test pre and post stress at 25°C. OR +110°C/85% RH for 264 hours. Electrical test pre and post stress at 25°C."	77 dice	5	3	82	0	10	Spares should be properly identified.
Temp Cycle	"JESD22-A104. -65°C to +150°C for 500 cycles or -40°C to 125°C for 1000 cycles. Electrical test pre and post stress at +25°C (required) and hot temp (optional). Read point at 0, 500, and 1000 (if applicable) cycles."	77 dice	5	3	82	0	15	Spares should be properly identified.
High Temperature Storage	Tested per JESD22-A103. 150°C storage for 1000hrs or 175°C storage for 500 hrs. Electrical test pre and post stress at 25°C.	45 dice	5	1	50	0	50	Spares should be properly identified.
High Temp Bake and Low Speed Ball Shear	Tested per JESD22-B117 Bake conditions 150°C for 1000hrs or 175°C for 500hrs. Low speed shear per condition A or high-speed shear per condition B"	30 shears	0	1	35	0		Spares should be properly identified.